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(12) **United States Design Patent**
Bell

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(54) **WIRE BONDING WEDGE TOOL**

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(73) Assignee: **COORSTEK, INC.**, Golden, CO (US)

(**) Term: **14 Years**

(21) Appl. No.: **29/524,165**

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(51) **LOC (10) Cl.** **15-09**

(52) **U.S. Cl.**
USPC **D15/144**; D15/199

(58) **Field of Classification Search**
USPC D8/14, 14.1, 29, 30; D15/144, 199; D24/187
CPC .. B23K 20/005; B23K 20/004; B23K 20/106; H01L 24/85
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a wire bonding wedge tool, as shown and described.

DESCRIPTION

FIG. **1** depicts a perspective view of a wire bonding wedge tool.

FIG. **2** depicts a second perspective view of the wire bonding wedge tool of FIG. **1**, wherein FIG. **2** is rotated axially 90 degrees relative to FIG. **1**.

FIG. **3** depicts a front side elevation view of the wire bonding wedge tool of FIG. **1**.

FIG. **4** depicts a right side elevation view of the wire bonding wedge tool of FIG. **1**.

FIG. **5** depicts a left side elevation view of the wire bonding wedge tool of FIG. **1**.

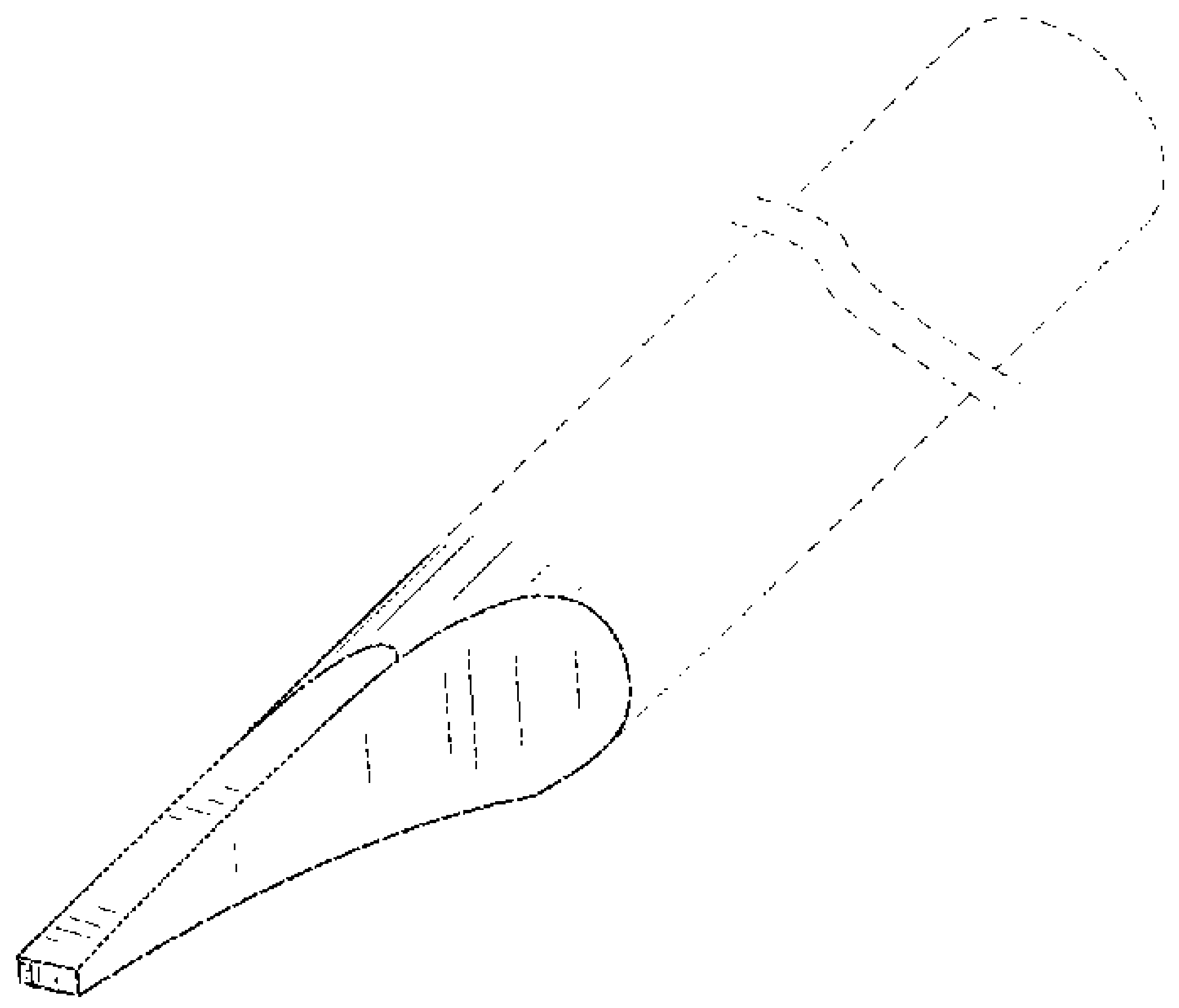
FIG. **6** depicts a rear side elevation view of the wire bonding wedge tool of FIG. **1**.

FIG. **7** depicts a top plan view of the wire bonding wedge tool of FIG. **6**; and,

FIG. **8** depicts a bottom plan view of the wire bonding wedge tool of FIG. **6**.

The broken lines in the figures depict portions of the wire bonding wedge tool that form no part of the claimed design.

1 Claim, 5 Drawing Sheets



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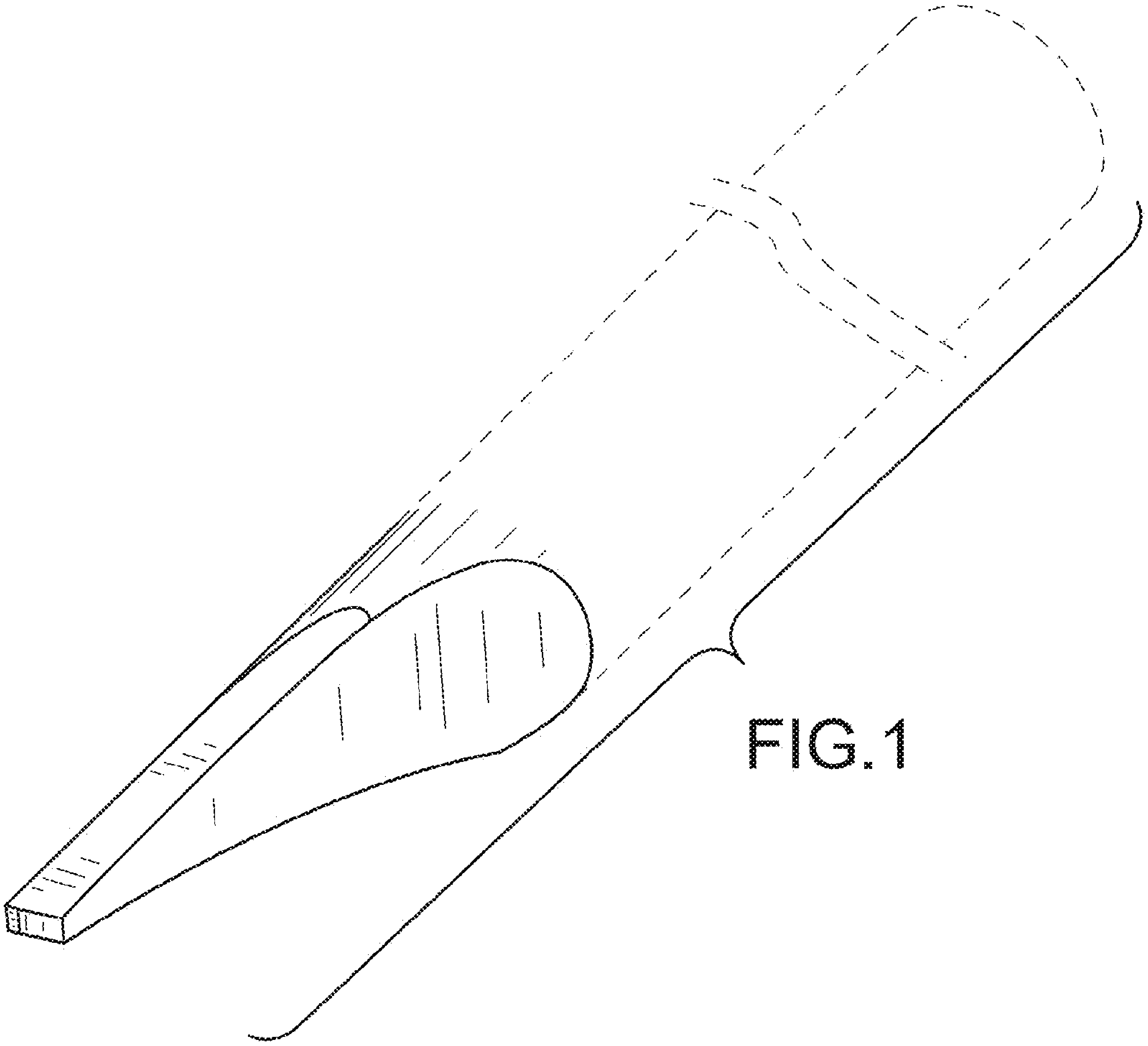

FIG.1

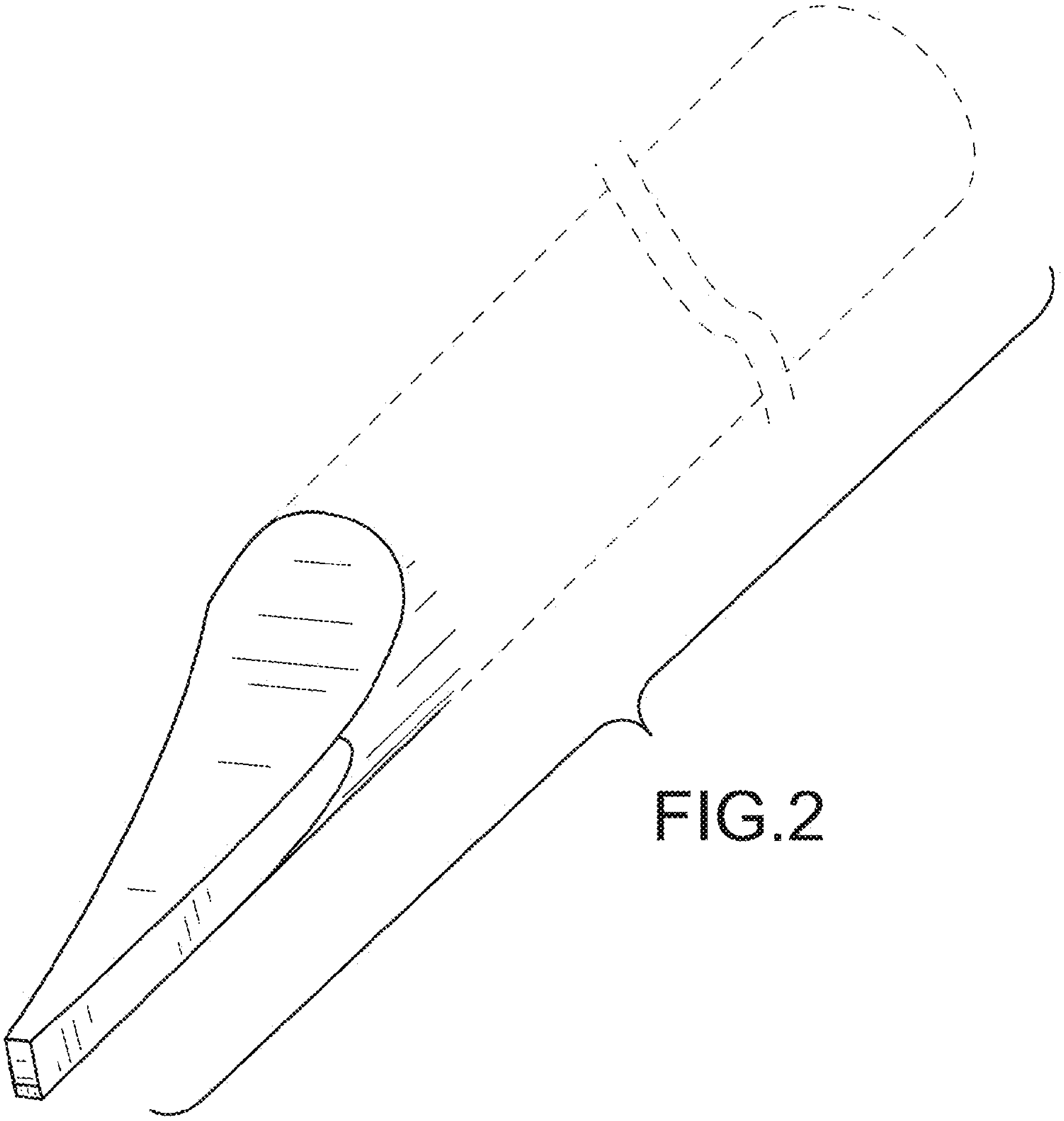

FIG.2

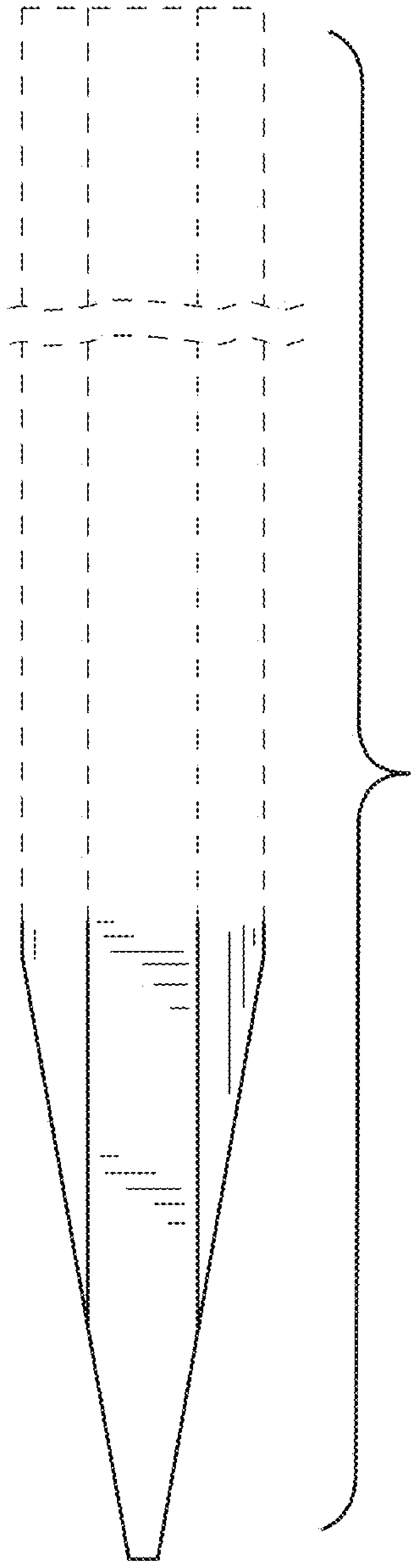

FIG.3

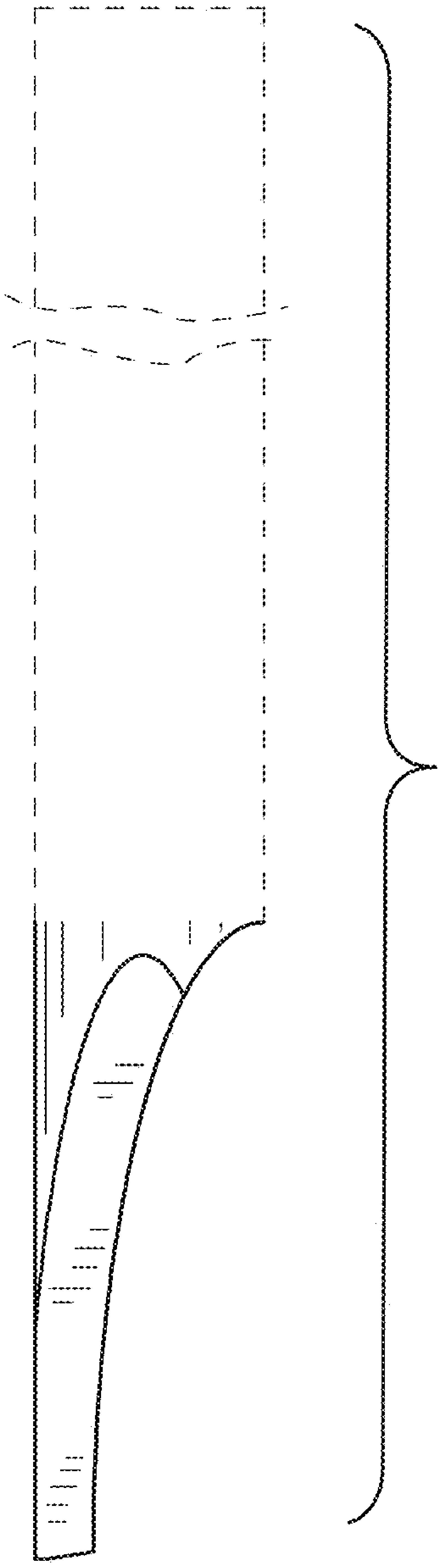

FIG.4

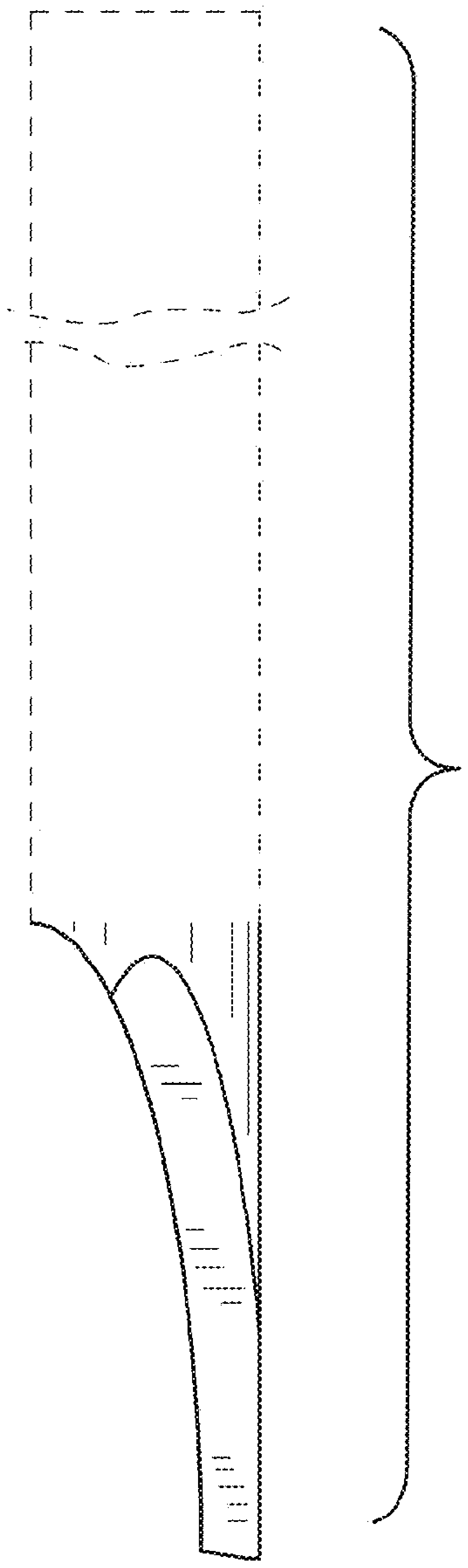

FIG.5

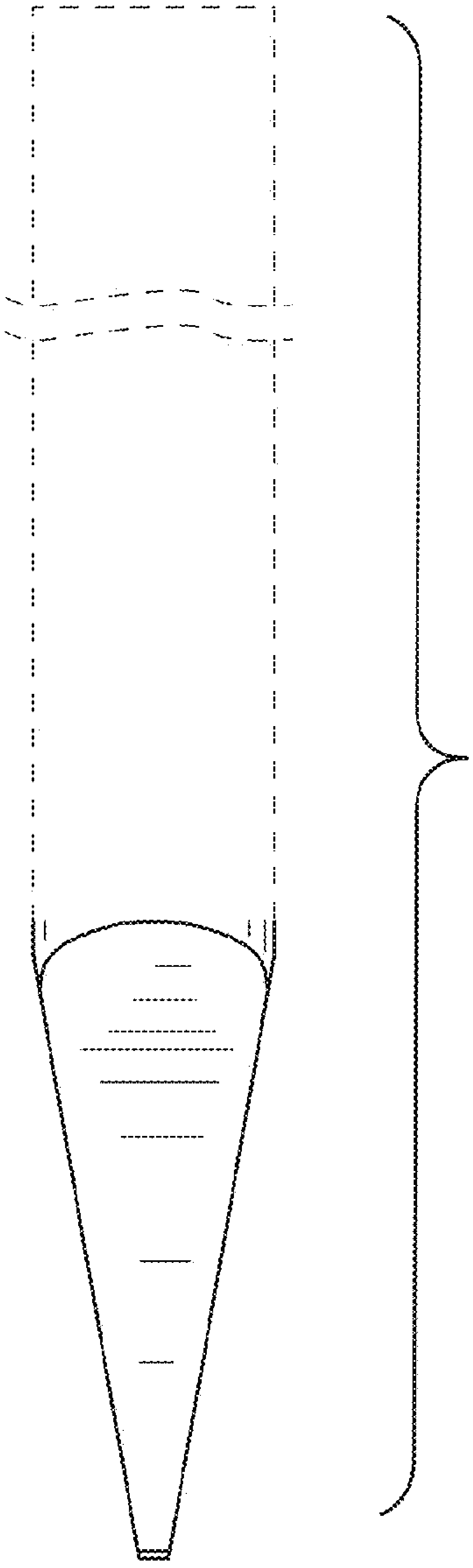

FIG.6

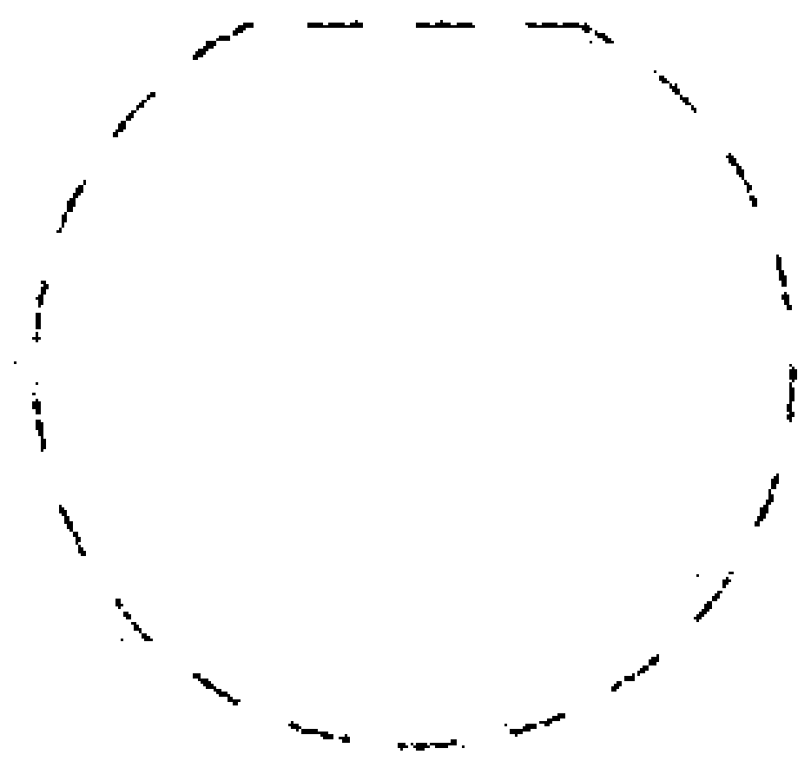

FIG.7

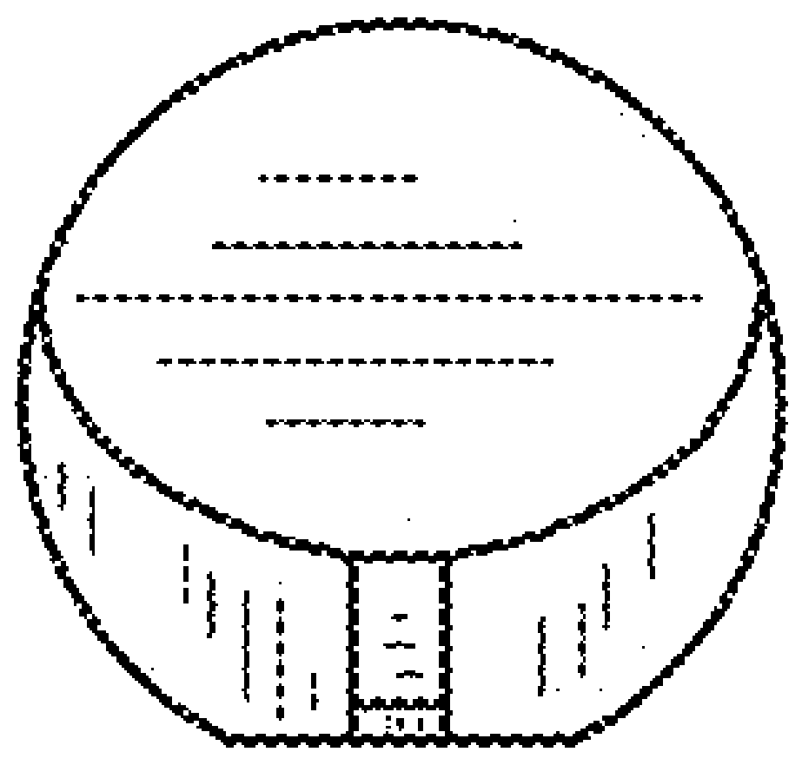

FIG.8